

Appl. No. 10/734,195

Date of Response: December 5, 2005

DFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/734,195
Applicant : Kwun-Yao Ho et al.
Filed : December 15, 2003
Title : HIGH-DENSITY MULTICHIP MODULE PACKAGE
TC/A.U. : 2813
Examiner : BRYANT, DELORIS S
Docket No. : 025796-00014

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Sir:

In response to the Official Action mailed September 14, 2005. Applicants respectfully request that the Examiner reconsider the amended application according to the following remarks.

Please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begin on page 4 of this paper.

Remarks/Arguments begin on page 7 of this paper.